

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-20	V
Gate-Source Voltage			V _{GSS}	±10	V
Continuous Drain Current (Note 5) V _{GS} = -4.5V	Steady State	T _A = +25°C T _A = +70°C T _C = +25°C	I _D	-18.0 -14.5 -40	A
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)			I _{DM}	-80	A
Maximum Continuous Body Diode Forward Current (Note 5)			I _S	-2.2	A
Avalanche Current (Note 7) L=0.1mH			I _{AS}	-23	A
Avalanche Energy (Note 7) L=0.1mH			E _{AS}	28	mJ

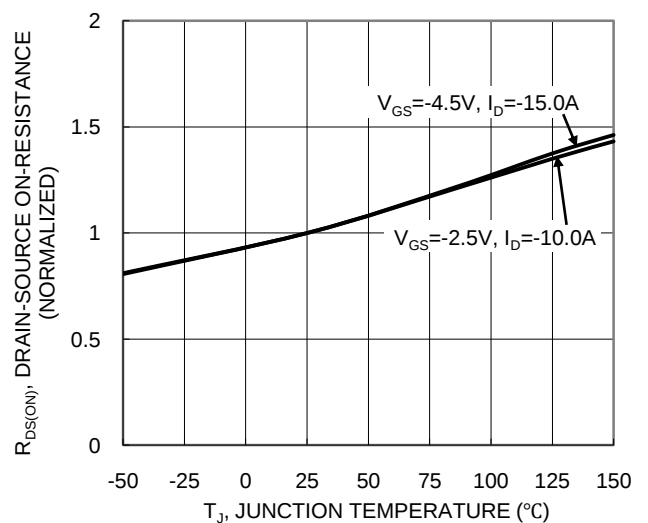
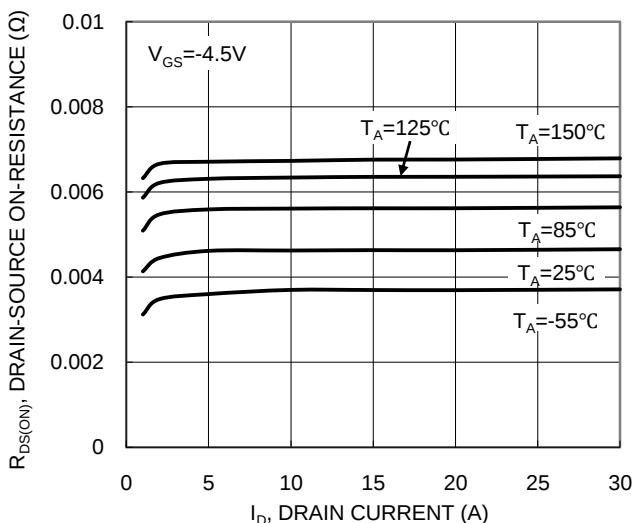
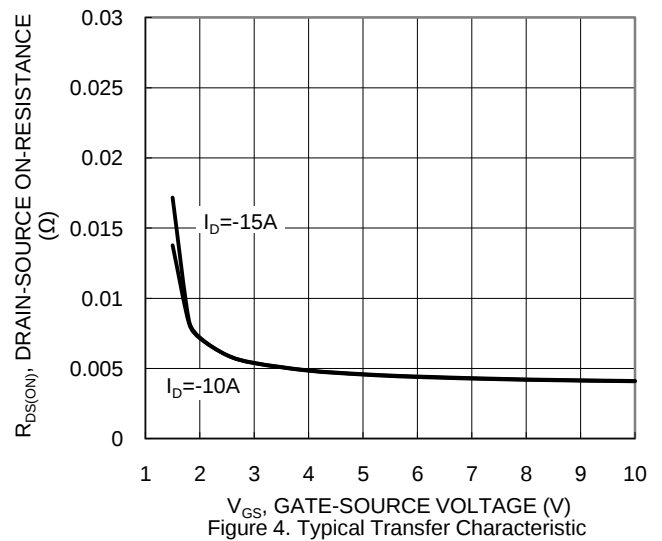
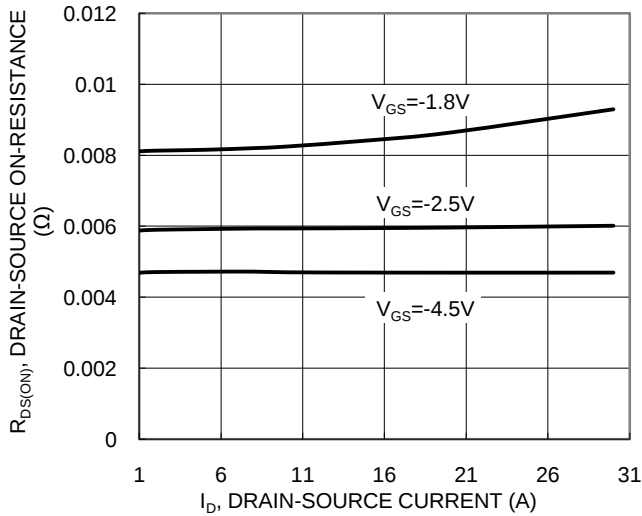
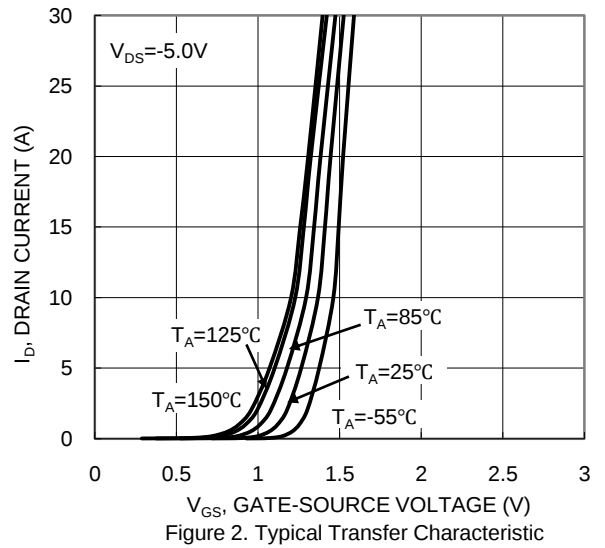
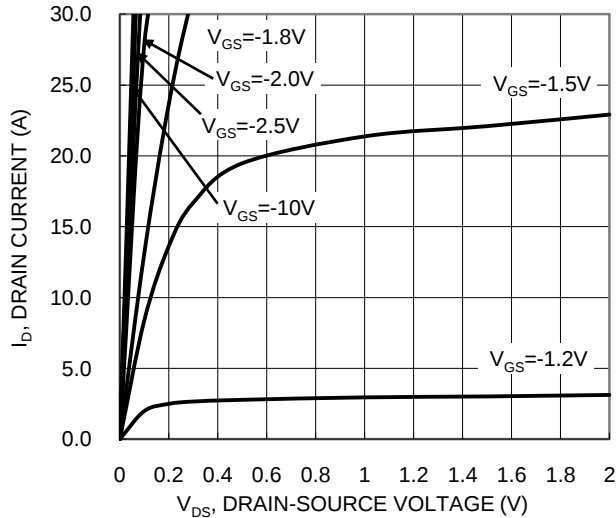
Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

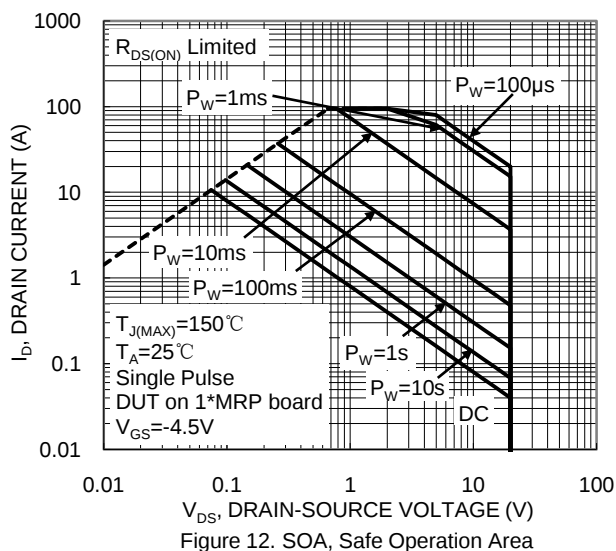
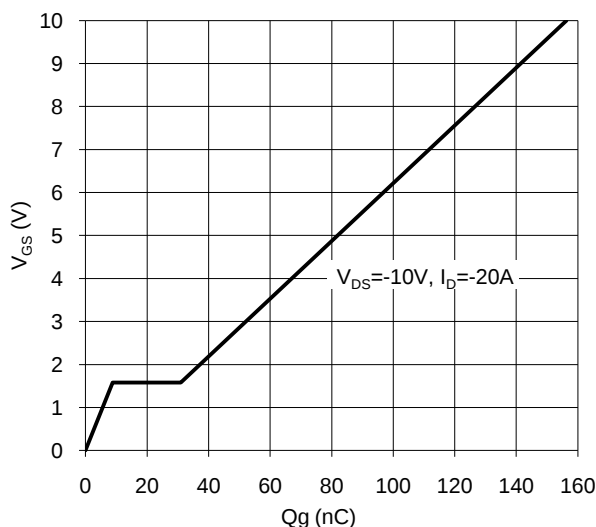
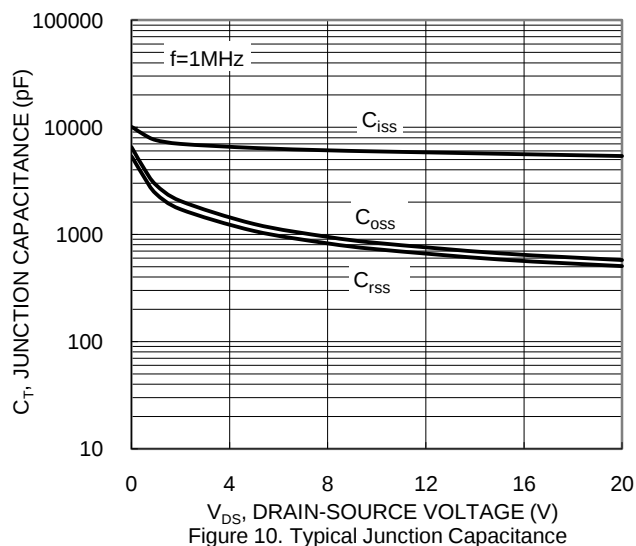
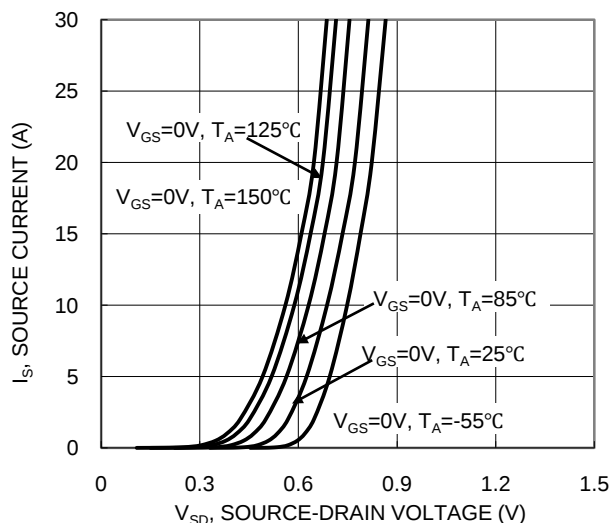
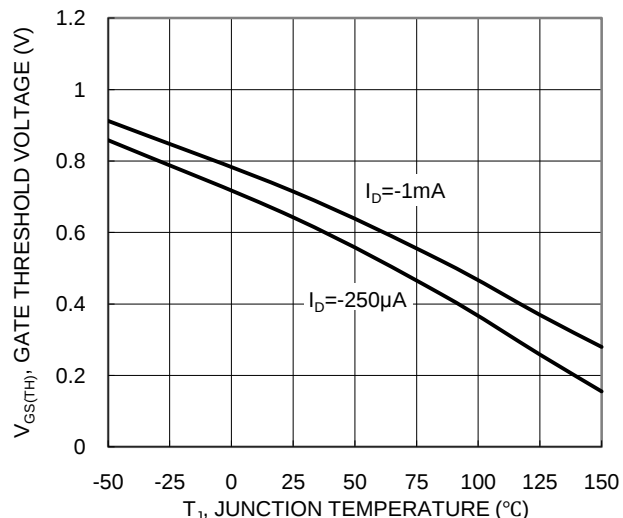
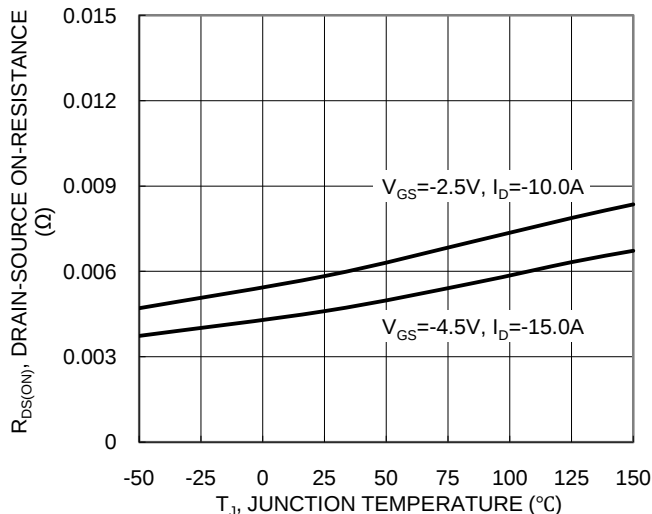
Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	P _D	2.3	W
	T _C = +25°C		41	
Thermal Resistance, Junction to Ambient	(Note 5)	R _{θJA}	56	°C/W
	(Note 6)		124	
Thermal Resistance, Junction to Case		R _{θJC}	6.8	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

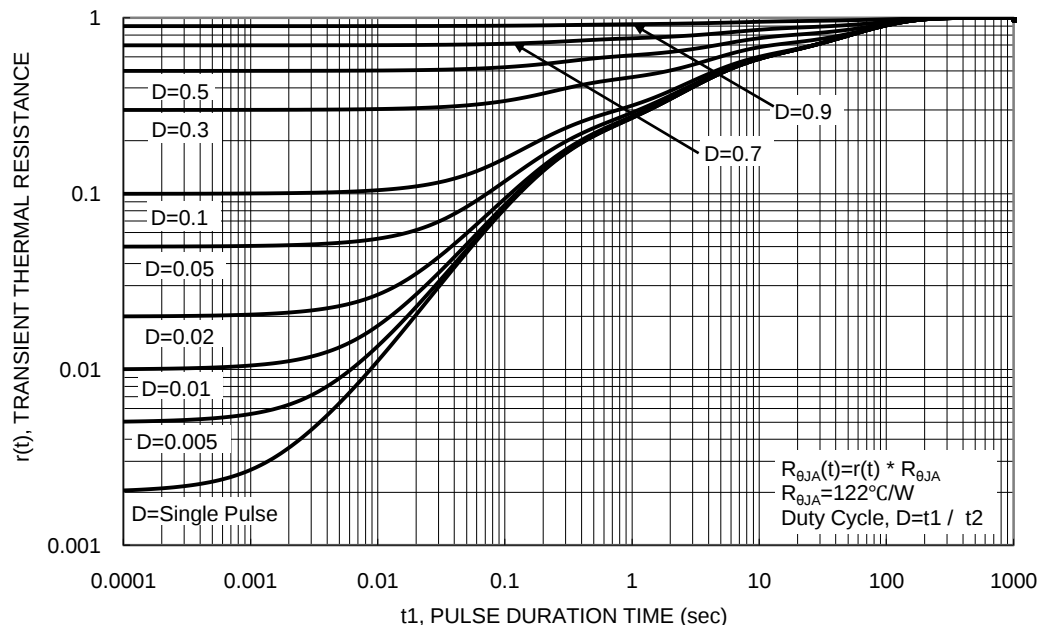
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-1	μA	V _{DS} = -16V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	-0.4	—	-1.0	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	4.2	6.7	mΩ	V _{GS} = -4.5V, I _D = -15A
		—	5.4	9.0		V _{GS} = -2.5V, I _D = -10A
		—	7	—		V _{GS} = -1.8V, I _D = -1A
Diode Forward Voltage	V _{SD}	—	-0.7	-1.2	V	V _{GS} = 0V, I _S = -10A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	—	5940	—	pF	V _{DS} = -10V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	835	—		
Reverse Transfer Capacitance	C _{rss}	—	728	—		
Gate Resistance	R _G	—	3.0	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge (V _{GS} = -4.5V)	Q _g	—	75	—	nC	V _{DD} = -10V, I _D = -20A
Total Gate Charge (V _{GS} = -10V)	Q _g	—	156	—		
Gate-Source Charge	Q _{gs}	—	8.8	—		
Gate-Drain Charge	Q _{gd}	—	22	—		
Turn-On Delay Time	t _{D(ON)}	—	10.7	—	ns	V _{GS} = -4.5V, V _{DD} = -10V, R _G = 1Ω, I _D = -10A
Turn-On Rise Time	t _R	—	23	—		
Turn-Off Delay Time	t _{D(OFF)}	—	121	—		
Turn-Off Fall Time	t _F	—	109	—		
Reverse Recovery Time	t _{RR}	—	60	—	ns	I _F = -10A, di/dt = 100A/μs
Reverse Recovery Charge	Q _{RR}	—	47	—	nC	I _F = -10A, di/dt = 100A/μs

- Notes:
5. R_{θJA} is determined with the device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. R_{θJC} is guaranteed by design while R_{θJA} is determined by the user's board design.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 7. UIS in production with L = 0.1mH, T_J = +25°C
 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to product testing.

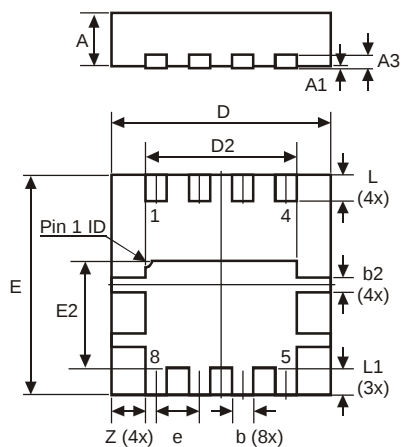






Package Outline Dimensions

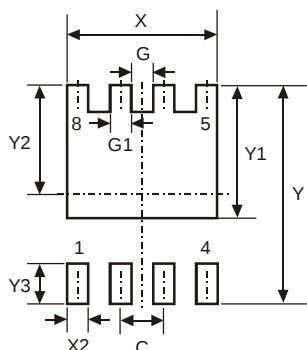
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



POWERDI3333-8			
Dim	Min	Max	Typ
D	3.25	3.35	3.30
E	3.25	3.35	3.30
D2	2.22	2.32	2.27
E2	1.56	1.66	1.61
A	0.75	0.85	0.80
A1	0	0.05	0.02
A3	—	—	0.203
b	0.27	0.37	0.32
b2	—	—	0.20
L	0.35	0.45	0.40
L1	—	—	0.39
e	—	—	0.65
Z	—	—	0.515
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.650
G	0.230
G1	0.420
Y	3.700
Y1	2.250
Y2	1.850
Y3	0.700
X	2.370
X2	0.420

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